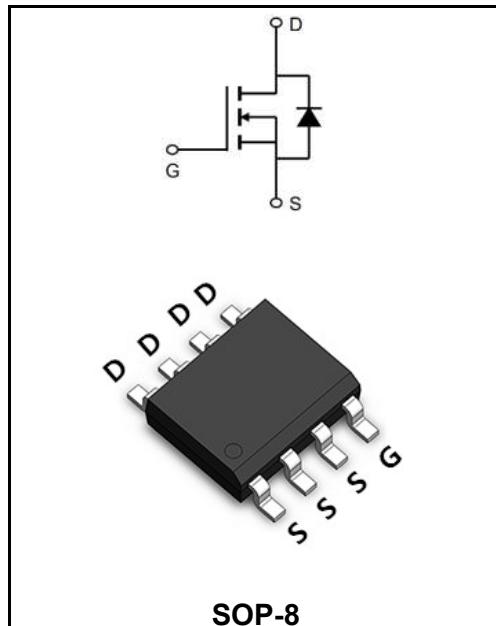


30V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

| | |
|-------------------------------|----------------------|
| I_D | 40A |
| V_{DSS} | 30V |
| $R_{DS(on)-typ}(@V_{GS}=10V)$ | < 9mΩ (Type: 7.5 mΩ) |


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

| Part Number | Package | Marking | Pack |
|-------------|---------|------------------|--------------|
| YFW40N03S | SOP-8 | YFW 40N03S XXXXX | 3000PCS/Tape |

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

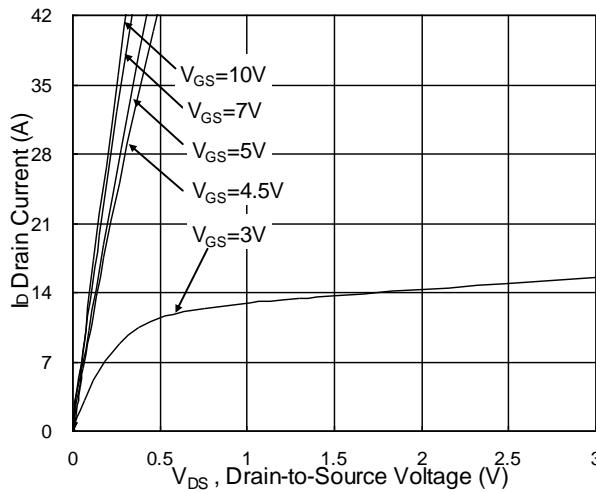
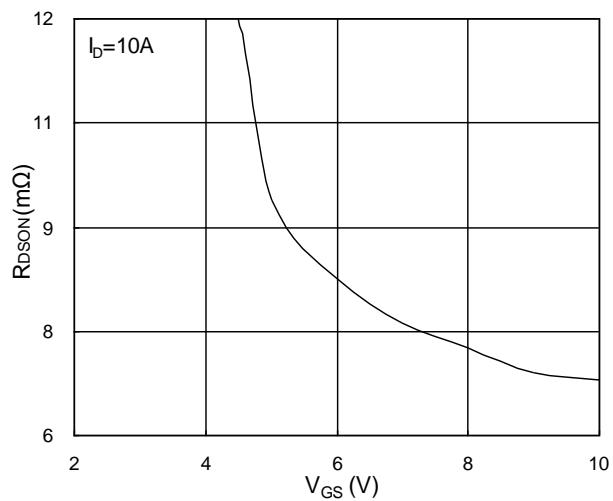
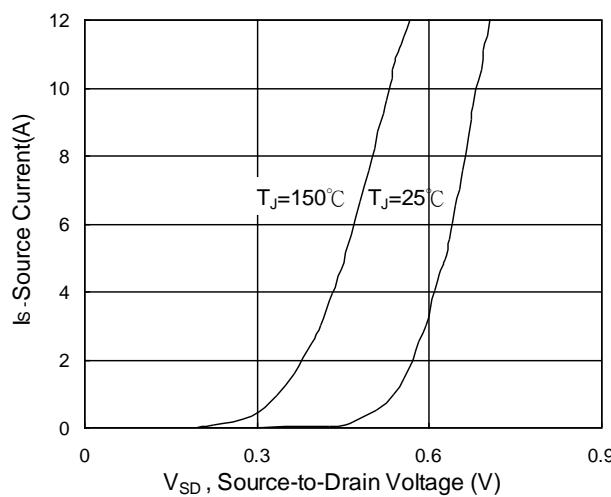
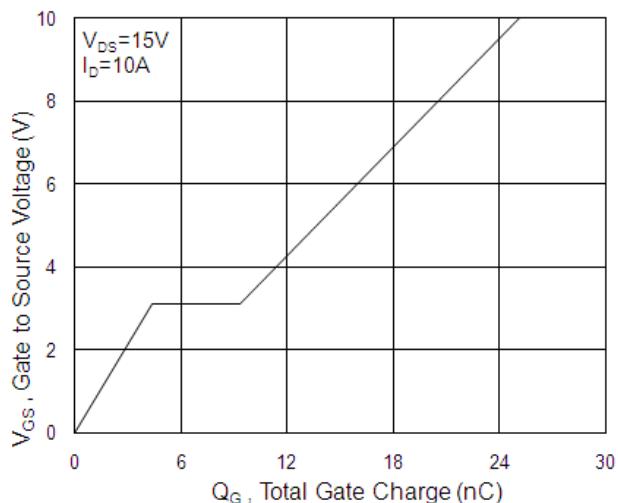
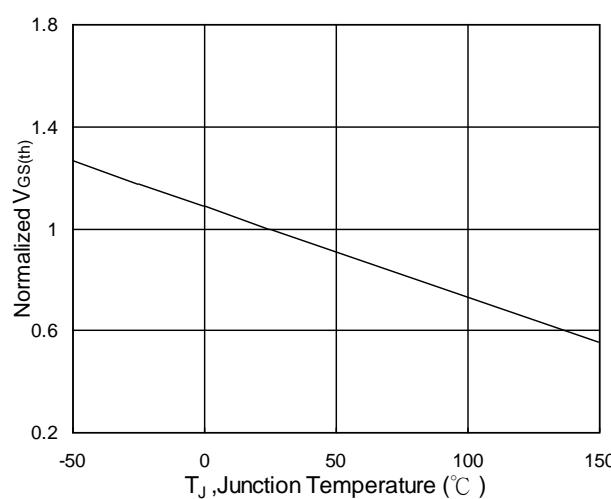
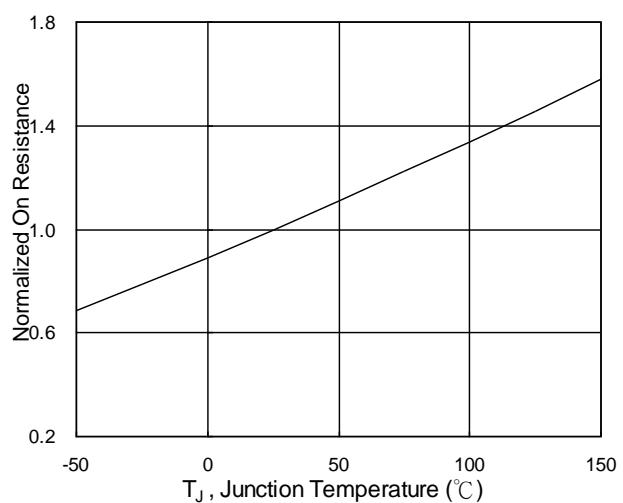
| Characteristics | Symbols | Value | Units |
|---|-----------------|-------------|-------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate - Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=25^\circ\text{C}$ | I_D | 40 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=70^\circ\text{C}$ | I_D | 8.2 | A |
| Pulsed Drain Current ² | I_{DM} | 82 | A |
| Single Pulse Avalanche Energy ³ | E_{AS} | 61 | mJ |
| Avalanche Current | I_{AS} | 35 | A |
| Total Power Dissipation ⁴ @ $T_A=25^\circ\text{C}$ | P_D | 1.5 | W |
| Storage Temperature Range | T_{STG} | -55 to +150 | °C |
| Operating Junction Temperature Range | T_J | -55 to +150 | °C |
| Thermal Resistance, Junction-to-Ambient ¹ | $R_{\theta JA}$ | 85 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | 36 | °C/W |

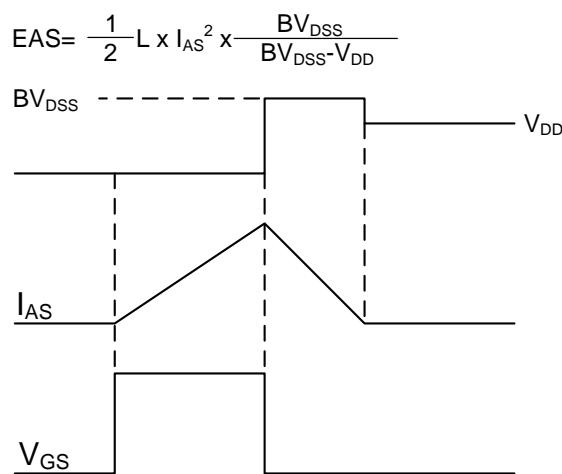
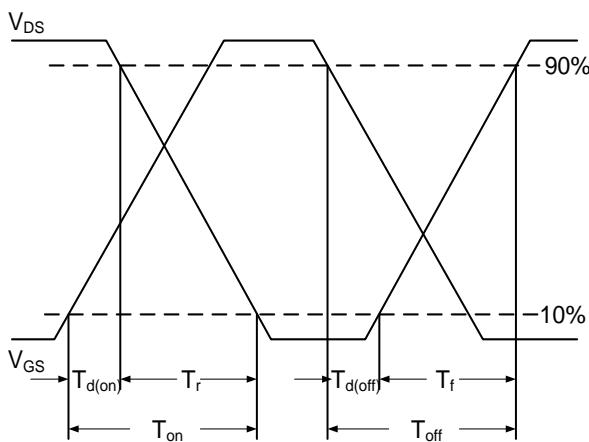
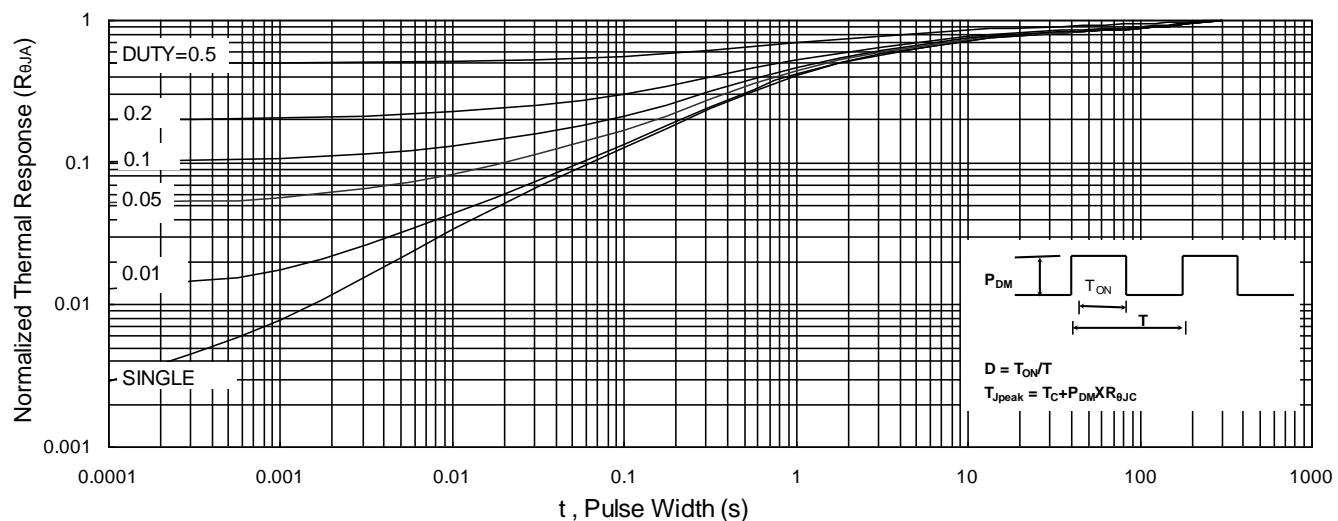
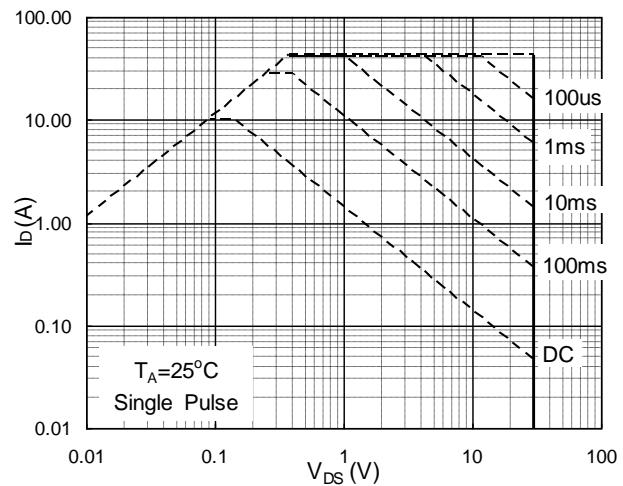
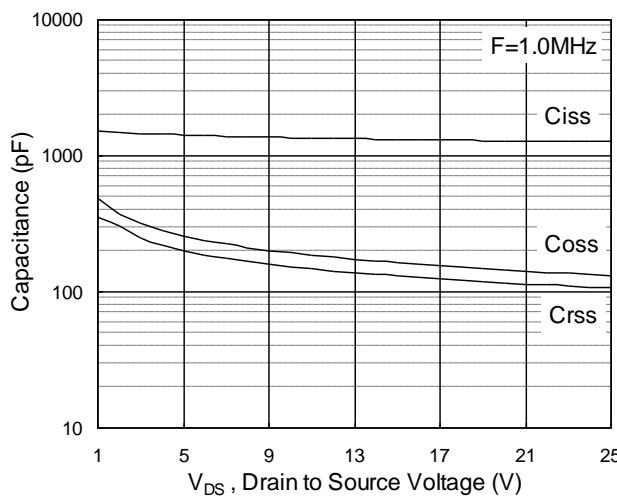
Maximum Ratings at Tc=25°C unless otherwise specified

| Characteristics | Test Condition | Symbols | Min | Typ | Max | Units |
|--|--|------------------------|-----|-------|-------|-------|
| Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | BV _{DSS} | 30 | - | - | V |
| BVDSS Temperature Coefficient | Reference to 25°C , I _D =1mA | ΔBV _{DSS/ΔTJ} | - | 0.027 | - | V/°C |
| Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =10A | R _{DS(ON)} | - | 7.5 | 9 | mΩ |
| | V _{GS} =4.5V, I _D =8A | | - | 11 | 14 | |
| Gate -Threshold Voltage | V _{DS} =V _{GS} , I _D =250uA | V _{GS(th)} | 1.2 | 1.5 | 2.5 | V |
| V _{GS(th)} Temperature Coefficient | | ΔV _{GS(th)} | - | -5.8 | - | mV/°C |
| Drain -Source Leakage Current | V _{DS} =24V , V _{GS} =0V , T _J =25°C | I _{DSS} | - | - | 1 | μA |
| | V _{DS} =24V , V _{GS} =0V , T _J =55°C | | - | - | 5 | |
| Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | I _{GSS} | - | - | ±100 | nA |
| Forward Transconductance | V _{DS} =5V, I _D =10A | g _{FS} | - | 5.8 | - | S |
| Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | R _g | - | 2.2 | 3.8 | |
| Total Gate Charge(4.5V) | V _{DS} =15V V _{GS} =4.5V I _D =10A | Q _g | - | 12.6 | 17.6 | nC |
| Gate-Source Charge | | Q _{gs} | - | 4.2 | 5.9 | |
| Gate-Drain Charge | | Q _{gd} | - | 5.1 | 7.1 | |
| Turn-on delay time | V _{DD} =15V V _{GS} =10V R _G =3.3 I _D =10A | t _{d(on)} | - | 6.2 | 12.4 | ns |
| Rise Time | | T _r | - | 59 | 106 | |
| Turn-Off Delay Time | | t _{d(OFF)} | - | 27.6 | 55 | |
| Fall Time | | t _f | - | 8.4 | 16.8 | |
| Input Capacitance | V _{DS} =15V V _{GS} =0V f=1.0MHz | C _{iss} | - | 1317 | 1845 | pF |
| Output Capacitance | | C _{oss} | - | 163 | 228.2 | |
| Reverse Transfer Capacitance | | C _{rss} | - | 131 | 183.4 | |
| Continuous Source Current ^{1,5} | V _G =V _D =0V , Force Current | I _s | - | - | 10.3 | A |
| Pulsed Source Current ^{2,5} | | I _{SM} | - | - | 42 | A |
| Diode Forward Voltage ² | V _{GS} =0V , I _s =1A , T _J =25°C | V _{SD} | - | - | 1.2 | V |
| Reverse Recovery Time | I _F =10A , dI/dt=100A/μs , T _J =25°C | t _{rr} | - | 12.5 | - | nS |
| Reverse Recovery Charge | | Q _{rr} | - | 5 | - | nC |

Note :

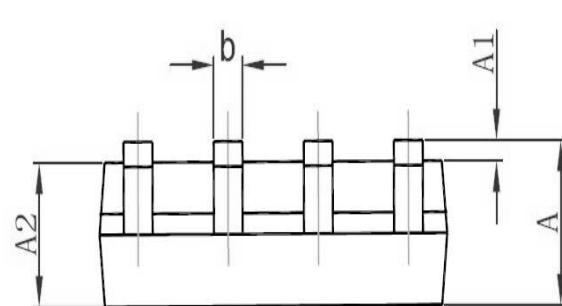
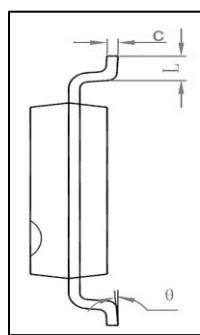
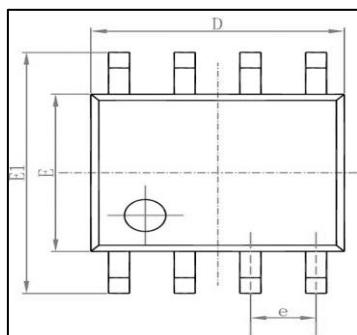
- 1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3 .The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=35A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves
Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. Gate-Source

Fig.3 Forward Characteristics of reverse

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs. T_J

Fig.6 Normalized $R_{DS(on)}$ vs. T_J

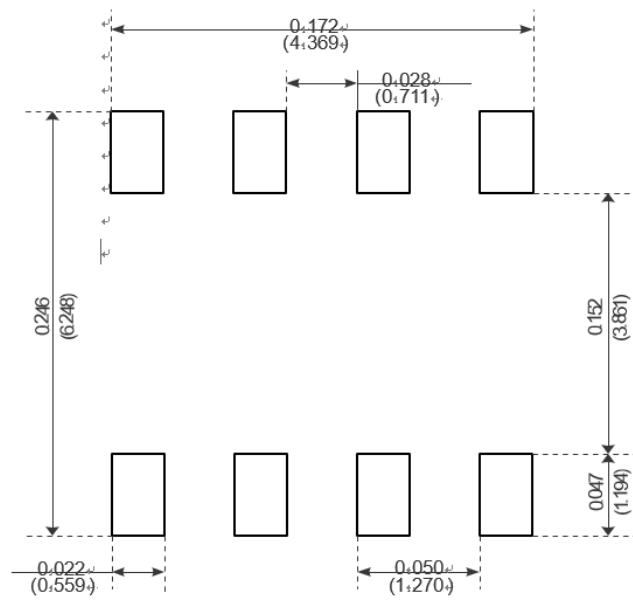
Ratings and Characteristic Curves


Package Outline Dimensions Millimeters

SOP-8



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.200 |
| E | 3.800 | 4.000 | 0.150 | 0.157 |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 |
| e | 1.270 (BSC) | | 0.050 (BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |



Recommended Minimum Pads